
The IEEE Custom Integrated Circuits Conference (CICC) is the premier IC development conference showcasing original and innovative analog and digital circuit techniques and emphasizing education of engineers at any level of experience.

The CICC 2017 conference theme is Energy Efficiency.

Papers Solicitation

CICC 2017 welcomes submissions of original and unpublished work on:

Power Management circuits and techniques for power generation, conversion, distribution and monitoring, aimed to reduce overall energy consumption, including energy scavenging and wireless charging.

Analog Circuits and Techniques for ultra low-voltage, ultra low-power and emerging technologies in biomedical, aerospace, automotive, energy, environment, and security applications, spacing from basic analog building blocks to silicon sensors, interfaces, and novel clock generation architectures.

Data Converters including novel Nyquist, oversampled or compressive sensing architectures, for ultra voltage, ultra low-power or very high-speed applications.

Wireless Transceiver and RF Circuits for very low-power and low data-rate links, wireless sensor networks and IoT applications, cellular connectivity, including M2M applications (LTE-M, NB-IoT), emerging broadband and MIMO networks (5G, WLAN), and millimeter-wave (radar, sensing and imaging).

Wireline Communications Circuits and Systems for electrical and optical communications, including serial links and components for intra-chip and chip-to-chip interconnections, high-speed memory and graphics interfaces, backplanes and long-haul communications.

Design Foundations on modeling, simulation, manufacturing and testing for circuit designers, that are tutorial in nature and mainly focused on advanced process nodes (FinFET, FD-SOI), DFM and DFT techniques, extremely reliable applications.

Emerging Technologies in biomedical, aerospace, automotive, energy, environment, IoT, and security applications, including micro-chemical and MEMS sensors and actuators, fluidic, organic, implantable and flexible electronics, novel image sensor and displays, emerging memories (especially NVM like MRAM, ReRAM), alternatives to CMOS scaling (non-silicon, and photonic technologies), and architectures, methodologies and manufacturing solutions to improve system integration (2.5D and 3D SoCs and SiPs, FPGAs).

Conference Technical Sessions and Events

Technical Sessions addressing a broad range of circuits, applications, design techniques, tools, test, reliability, and emerging technologies, and providing education on new, state-of-the-art developments is the core of the CICC technical program.

Educational sessions instructed by recognized invited speakers who are among the best in the industry are included in the conference. They are valuable opportunities to refresh key skills in traditional circuit-design methods and acquire knowledge in vital new areas in analog, digital, and RF integrated circuit design.

Panels, Forums and a Plenary Session provide a platform for leaders from the IC industry and academia present highlights on new field of research and development related to circuit design and to debate key issues and controversial topics. CICC panels are well known for their lively and thought-provoking discussion and audience participation.

An Exhibit, is where semiconductor manufacturers, IP providers, SW tool suppliers, design-service houses, and technical book publishers offer their products. Our Welcome Reception, Conference Receptio, Conference Luncheon and Exhibit with food and beverage, provide additional opportunities for discussion and peer networking.

Papers Submission

Papers must be 4 pages in length, follow the paper preparation guidelines, be print-ready and submitted electronically in PDF format using the CICC website (www.ieee-cicc.org), and include a complete copyright form. Appropriate company and government clearances MUST be obtained prior to submission. Papers must report an original unpublished work and concisely explain how the state-of-the-art is advanced, including results. Circuit-design papers must include measured experimental results that substantiate performance claims.

Deadline for submission of technical papers is November 7, 2016. Authors of accepted papers will be notified by email by January 15, 2017. Awards include Best Paper and Best Student Paper. Top-rated papers are also eligible for publication in a special issue of the IEEE Journal of Solid State Circuits and the IEEE Transactions on Circuits Systems.